

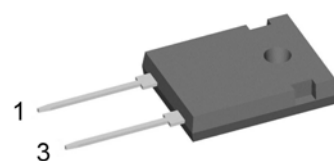
HiPerFRED²

V_{RRM}	=	300 V
I_{FAV}	=	30 A
t_{rr}	=	35 ns

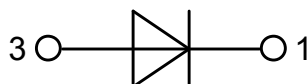
High Performance Fast Recovery Diode
Low Loss and Soft Recovery
Single Diode

Part number

DPG30I300HA



Backside: cathode



Features / Advantages:

- Planar passivated chips
- Very low leakage current
- Very short recovery time
- Improved thermal behaviour
- Very low I_{rm} -values
- Very soft recovery behaviour
- Avalanche voltage rated for reliable operation
- Soft reverse recovery for low EMI/RFI
- Low I_{rm} reduces:
 - Power dissipation within the diode
 - Turn-on loss in the commutating switch

Applications:

- Antiparallel diode for high frequency switching devices
- Antisaturation diode
- Snubber diode
- Free wheeling diode
- Rectifiers in switch mode power supplies (SMPS)
- Uninterruptible power supplies (UPS)

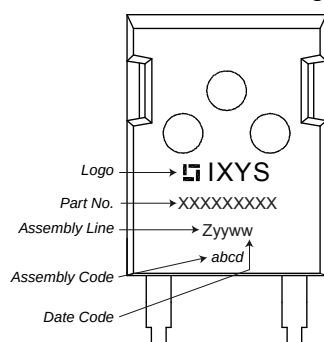
Package: TO-247

- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0

Fast Diode				Ratings				
Symbol	Definition	Conditions		min.	typ.	max.	Unit	
V _{RSM}	max. non-repetitive reverse blocking voltage	T _{VJ} = 25°C				300	V	
V _{RRM}	max. repetitive reverse blocking voltage	T _{VJ} = 25°C				300	V	
I _R	reverse current, drain current	V _R = 300 V	T _{VJ} = 25°C			1	μA	
		V _R = 300 V	T _{VJ} = 150°C			0.1	mA	
V _F	forward voltage drop	I _F = 30 A	T _{VJ} = 25°C			1.34	V	
		I _F = 60 A				1.63	V	
		I _F = 30 A	T _{VJ} = 150°C			1.06	V	
		I _F = 60 A				1.39	V	
I _{FAV}	average forward current	T _C = 140°C rectangular d = 0.5	T _{VJ} = 175°C			30	A	
V _{FO}	threshold voltage	} for power loss calculation only		T _{VJ} = 175°C		0.70	V	
r _F	slope resistance					10.5	mΩ	
R _{thJC}	thermal resistance junction to case					0.95	K/W	
R _{thCH}	thermal resistance case to heatsink				0.25		K/W	
P _{tot}	total power dissipation	T _C = 25°C				160	W	
I _{FSM}	max. forward surge current	t = 10 ms; (50 Hz), sine; V _R = 0 V		T _{VJ} = 45°C		360	A	
C _J	junction capacitance	V _R = 150 V f = 1 MHz		T _{VJ} = 25°C	42		pF	
I _{RM}	max. reverse recovery current	} I _F = 30 A; V _R = 200 V -di _F /dt = 200 A/μs		T _{VJ} = 25°C	3		A	
				T _{VJ} = 125°C	7		A	
t _{rr}	reverse recovery time			T _{VJ} = 25°C	35		ns	
				T _{VJ} = 125°C	55		ns	

Package TO-247			Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit
I_{RMS}	RMS current	per terminal			50	A
T_{VJ}	virtual junction temperature		-55		175	°C
T_{op}	operation temperature		-55		150	°C
T_{stg}	storage temperature		-55		150	°C
Weight				6		g
M_D	mounting torque		0.8		1.2	Nm
F_C	mounting force with clip		20		120	N

Product Marking



Part number

D = Diode
P = HiPerFRED
G = extreme fast
30 = Current Rating [A]
I = Single Diode
300 = Reverse Voltage [V]
HA = TO-247AD (2)

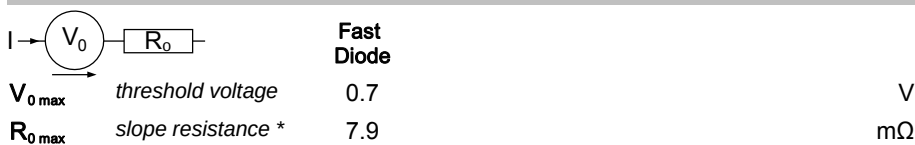
Ordering	Part Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	DPG30I300HA	DPG30I300HA	Tube	30	507313

Similar Part	Package	Voltage class
DPG30I300PA	TO-220AC (2)	300
DPF30I300PA	TO-220AC (2)	300

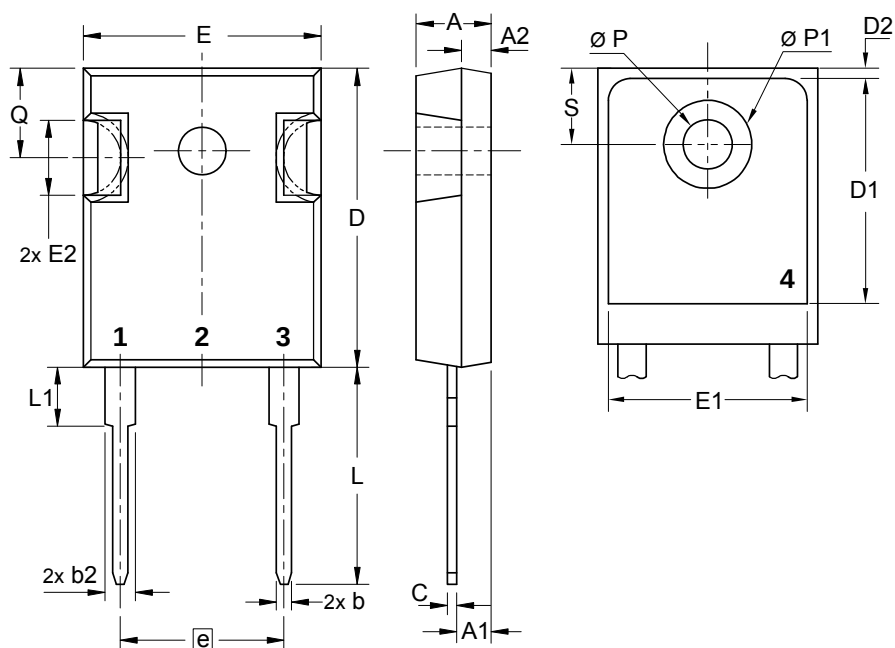
Equivalent Circuits for Simulation

* on die level

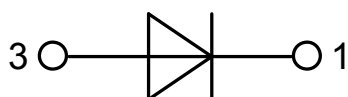
$T_{VJ} = 175^{\circ}\text{C}$



Outlines TO-247



Sym.	Inches		Millimeter	
	min.	max.	min.	max.
A	0.185	0.209	4.70	5.30
A1	0.087	0.102	2.21	2.59
A2	0.059	0.098	1.50	2.49
D	0.819	0.845	20.79	21.45
E	0.610	0.640	15.48	16.24
E2	0.170	0.216	4.31	5.48
e	0.430 BSC		10.92 BSC	
L	0.780	0.800	19.80	20.30
L1	-	0.177	-	4.49
Ø P	0.140	0.144	3.55	3.65
Q	0.212	0.244	5.38	6.19
S	0.242 BSC		6.14 BSC	
b	0.039	0.055	0.99	1.40
b2	0.065	0.094	1.65	2.39
b4	0.102	0.135	2.59	3.43
c	0.015	0.035	0.38	0.89
D1	0.515	-	13.07	-
D2	0.020	0.053	0.51	1.35
E1	0.530	-	13.45	-
Ø P1	-	0.29	-	7.39



Fast Diode

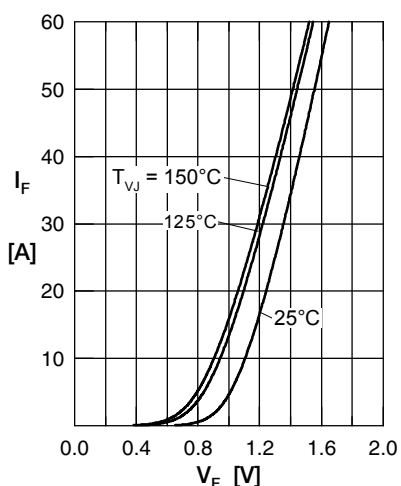


Fig. 1 Forward current I_F versus V_F

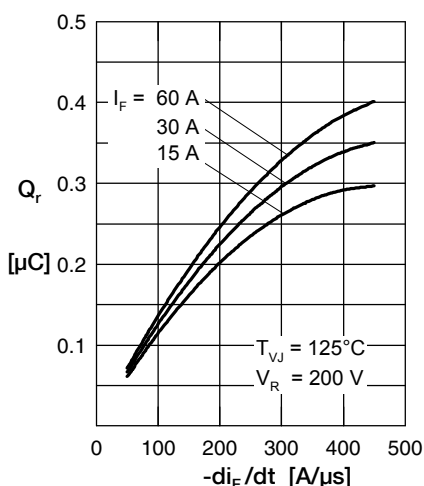


Fig. 2 Typ. reverse recov. charge Q_r versus $-di_F/dt$

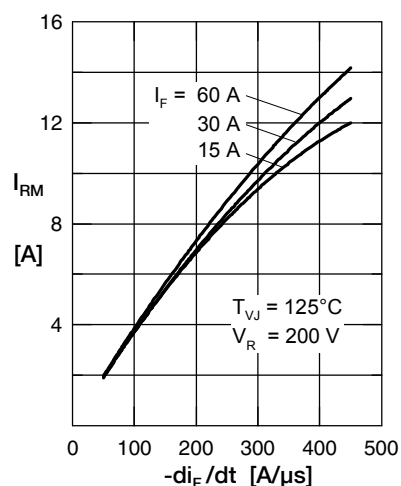


Fig. 3 Typ. peak reverse current I_{RM} versus $-di_F/dt$

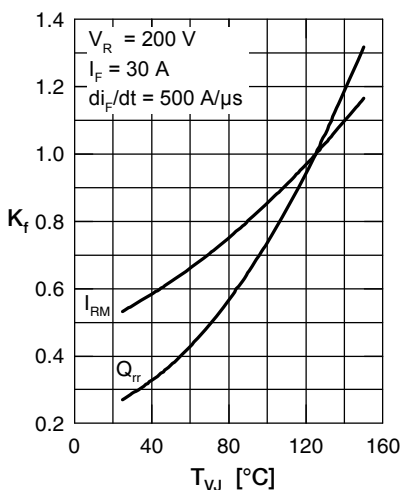


Fig. 4 Typ. dynamic parameters Q_r , I_{RM} versus T_{VJ}

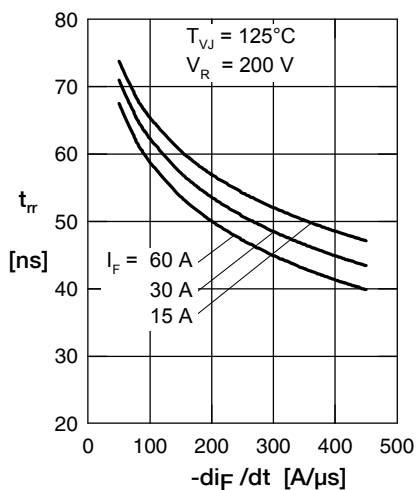


Fig. 5 Typ. recovery time t_{rr} versus $-di_F/dt$

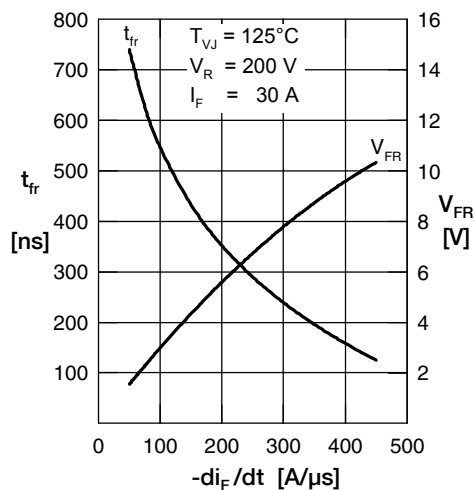


Fig. 6 Typ. peak forward voltage V_{FR} and t_{fr} versus di_F/dt

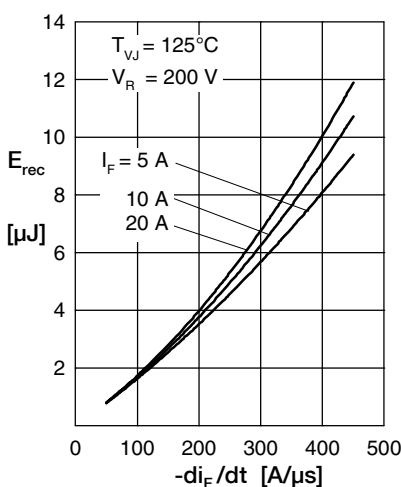


Fig. 7 Typ. recovery energy E_{rec} versus $-di_F/dt$

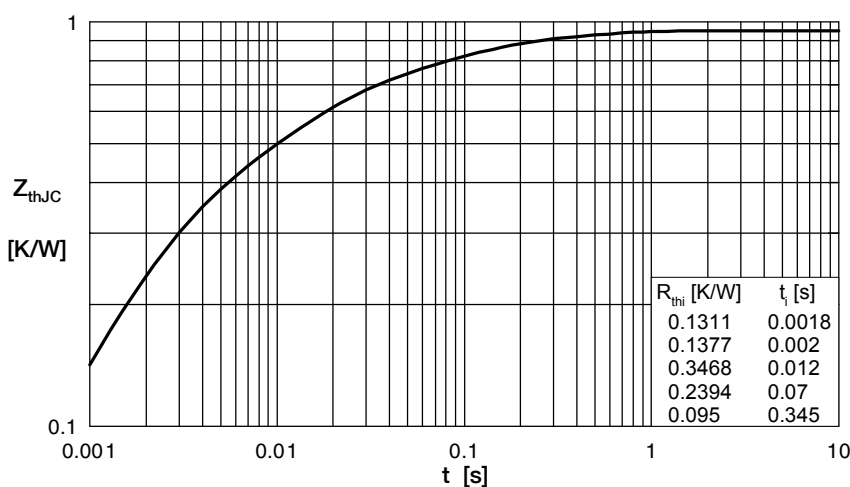


Fig. 8 Transient thermal impedance junction to case